

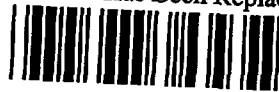
ABSTRACT:

Method of wave-soldering assembled units.

The invention relates to a method of wave-soldering assembled units (12) which are conducted over a soldering unit (13) by means of a transport device (10), solder (16) being propelled against the assembled units (12) in a turbulent zone via a first turbulent soldering wave (20) at an acute angle (α_1) in the transport direction (11) and subsequently
5 via a quiet soldering wave (22) approximately at right angles. To avoid cold soldered spots and shadow regions, the invention provides that in addition solder (16) is propelled against the assembled units (12) via a second turbulent wave (21) at an acute angle (α_2) against the transport direction (11) in the turbulent zone.

Fig. 1.

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